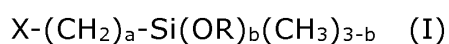


CLAIMS

[1] A composition comprising:
an alkali-soluble resin which is a polymer comprising a
carboxyl-containing polymerization unit and an alkoxysilyl-
containing polymerization unit,
a polysiloxane,
a diazonaphthoquinone derivative,
a compound generating acid or base when exposed to
heat or light, and
a solvent.

[2] The composition according to claim 1, wherein said
carboxyl-containing polymerization unit is derived from an
unsaturated carboxylic acid, an unsaturated carboxylic
anhydride, or a mixture thereof.

[3] The composition according to claim 1 or 2, wherein said
alkoxysilyl-containing polymerization unit is derived from a
monomer represented by the following formula (I):



in which

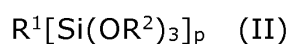
X is a vinyl, styryl or (meth)acryloyloxy group;

R is methyl or ethyl group;

a is an integer of 0 to 3; and

b is an integer of 1 to 3.

[4] The composition according to any of claims 1 to 3,
wherein said polysiloxane is derived from a monomer
represented by the following formula (II):



in which

p is an integer of 1 to 3;

R¹ is hydrogen or a p-valent straight, branched or cyclic
hydrocarbon group which has 20 or less carbon atoms and
which may contain oxygen or nitrogen, provided that any

hydrogen of the hydrocarbon group may be replaced with fluorine; and

each R² is independently hydrogen or an alkyl group having 1 to 10 carbon atoms.

[5] The composition according to any of claims 1 to 4, wherein said compound generating acid or base when exposed to heat or light is a photo acid- or base-generator whose absorbance ratio at 365 nm/436 nm or at 365 nm/405 nm is 5/1 or more.

[6] The composition according to any of claims 1 to 5, wherein said alkali-soluble resin has a weight average molecular weight of 3000 to 50000.

[7] The composition according to any of claims 1 to 6, wherein said polysiloxane has a weight average molecular weight of 800 to 15000.

[8] The composition according to any of claims 1 to 7, wherein the mixing ratio of said alkali-soluble resin and said polysiloxane is 5:95 to 95:5 by weight.

[9] A method for forming a cured film, comprising:
coating a substrate with the composition according to any of claims 1 to 8, to form a coating film;
exposing the coating film to light;
developing the exposed film with an alkali developer, to form a pattern; and
heating the obtained pattern.

[10] The method for forming a cured film, according to claim 9; which further comprises the step of exposing the whole film surface to light before the step of heating the obtained pattern.

[11] A cured film produced by a method comprising:

coating a substrate with the composition according to any of claims 1 to 8, to form a coating film;
exposing the coating film to light;
developing the exposed film with an alkali developer, to form a pattern; and
heating the obtained pattern.

[12] A device comprising the cured film according to claim 11.